

ASX RELEASE

10 March 2025

ASX: NVU

Embedded World 2025 Presentation

Nanoveu positioned to accelerate growth in AI-driven edge semiconductor solutions

Nanoveu Limited ("Nanoveu" or the "Company") (ASX: NVU), advises of its participation at the embedded world 2025 Conference & Exhibition being held between 11 to 13 March 2025 in Nuremberg, Germany.

The presentation materials are attached for the information of investors and shareholders and can also be accessed, together with an animated version, via the "Presentations" page of the Company's website: www.nanoveu.com/investor-centre/presentations/.

This announcement has been authorised for release by the Board of Directors.

-Ends-

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About Nanoveu Limited

Further details on the Company can be found at <https://nanoveu.com/>.

EMASS

EMASS is a pioneering technology company specialising in the design and development of advanced systems-on-chip (SoC) solutions. These SoCs enable ultra-low-power, AI-driven processing for smart devices, IoT applications, and 3D content transformation. With its industry-leading technology, EMASS will enhance Nanoveu's portfolio, empowering a wide range of industries with efficient, scalable AI capabilities, further positioning Nanoveu as a key player in the rapidly growing 3D content, AI and edge computing markets.

EyeFly3D™

The EyeFly3D™ platform is a comprehensive solution for delivering glasses-free 3D experiences across a range of devices and industries. At its core, EyeFly3D™ combines advanced screen technology, sophisticated software for content processing, and now, with the integration of EMASS's ultra-low-power SoC, powerful hardware.

Nanoshield™ - is a self-disinfecting film that uses a patented polymer of embedded Cuprous nanoparticles to provide antiviral and antimicrobial protection for a range of applications, from mobile covers to industrial surfaces. Applications include:

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Nanoshield™ Marine, which prevents the growth of aquatic organisms on submerged surfaces like ship hulls, and

Nanoshield™ Solar, designed to prevent surface debris on solar panels, thereby maintaining optimal power output.

Forward Looking Statements

This announcement contains 'forward-looking information' that is based on the Company's expectations, estimates and projections as of the date on which the statements were made. This forward-looking information includes, among other things, statements with respect to the Company's business strategy, plans, development, objectives, performance, outlook, growth, cash flow, projections, targets and expectations and related expenses. Generally, this forward-looking information can be identified by the use of forward-looking terminology such as 'outlook', 'anticipate', 'project', 'target', 'potential', 'likely', 'believe', 'estimate', 'expect', 'intend', 'may', 'would', 'could', 'should', 'scheduled', 'will', 'plan', 'forecast', 'evolve' and similar expressions. Persons reading this announcement are cautioned that such statements are only predictions, and that the Company's actual future results or performance may be materially different. Forward-looking information is subject to known and unknown risks, uncertainties and other factors that may cause the Company's actual results, level of activity, performance, or achievements to be materially different from those expressed or implied by such forward looking information.

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An applied technology company



embeddedworld 2025 Presentation

Exhibition&Conference

[Animated version of the presentation can be found here](#)

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AUTHORISATION This document has been authorised for release by the Company's Board of Directors.

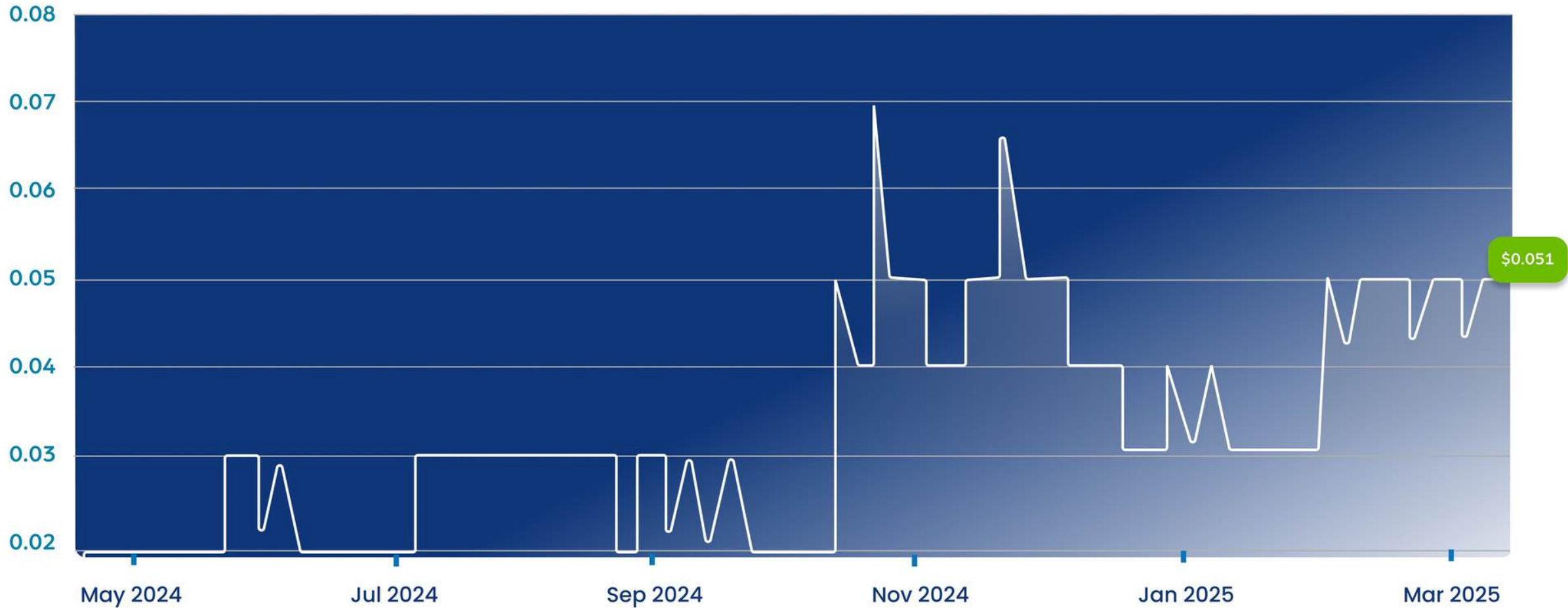
Capital Structure

Nanoveu Share Price

ASX - Delayed Quote - AUD
Nanoveu Limited (NVU.AX)

1D 5D 1M 6M YTD **1Y** 5Y All

\$0.051 ↑155.00% +0.031 1Y



Capital Structure*

ASX Code **NVU**

Shares on Issue **742.4m**

Options on Issue **235.3m**

Performance Rights on Issue **168.9m**

Previous Close **\$0.051**

Average Volume **3.27m**

Market Cap **\$37.86m**

*Post EMASS acquisition settlement (includes 172.4m shares + 83.3 performance rights)

Our Board



DR. DAVID PEVCIC
Executive Chairman

- Experienced professional and investor in the resources and technology sector.
- Non-Executive Chairman at Battery Age Minerals Ltd (ASX: BM8).
- Non-Executive Director at Infant Resources (ASX: 188).
- Holds a Bsc, MBBS, from the university of Western Australia.



ALFRED CHONG
Group Chief Executive Officer

- Founder Of Nanoveu, Has 30+ Years Of Experience In Scaling Companies And Trade Sales.
- Former CEO Of: Atex Media Command (APAC) ,THISS Technologies ,121View.
- Former CMO At 3D International.



STEVE APEDAILE
Non-Executive Director

- 30 Years Of Experience In Accounting.
- Worked At KPMG And Horwath Hong Kong.
- Fellow Of The ICAEW.
- Member Of The AICD.
- Executive Chairman Of Sprintex (ASX:SIX).



DR. MICHAEL WINLO
Non-Executive Director

- Former CEO Of Linear Clinical Research.
- Former Health Lead At Palantir (NYSE:PLTR).
- Holds An MBA From Stanford And An MBBS From UWA.

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Semiconductor Leadership Team



"We are positioning ourselves to meet growing global demand for low energy but powerful chips driven by the increasing demand for AI-supported applications."



"EMASS's ultra-low-power semiconductor technology has remarkable potential to transform AI enabled hardware, addressing a critical industry need for more efficient edge computing."

Mark Goranson
CEO of Semiconductor Technology

Notable Positions

- Vice President of global operations, TE connectivity (NYSE: TEL).
- Senior Vice President of Fab Operations, ON Semiconductor (NASDAQ: ON).
- Vice President of Fab Operations Freescale Semiconductor (NYSE: FSL).
- Early member of Intel Corporation (NASDAQ: INTC) for 18-years.
- Holds a B.Sc. in Physics/Electronics from New Mexico Tech.

Dr. Mohamed M. Aly
Founder of EMASS

Notable Positions

- Associate Professor at NTU Singapore, specializing in AI computing systems.
- Former Postdoc at Stanford (2014–2017).
- Senior IEEE Member.
- Collaborated with Stanford and TSMC.
- Recipient of the Nanyang Education Award (2023).
- Holds a Ph.D. from EPFL.



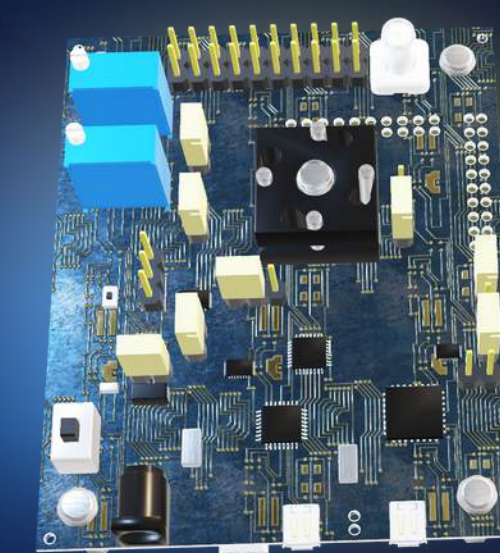
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Semiconductor And System On Chip (SoC) For AI Computing "On The Edge"

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EMASS-I2R
MOSCHIP
ECS-DOT
2231
Singapore



The Backbone of Modern Tech – Semiconductors & SoCs power healthcare, automotive, and smart IoT, making devices faster & more intelligent.

Compact & Energy-Efficient – Low-power, high-performance AI processing, perfect for next-gen connected technology.

Major Sectors Driving Demand for Energy Efficient AI Infrastructure

Aerospace And Defense

- Drones and UAVs for navigation, video processing and communication
- Military radar and surveillance

Consumer Electronics

- Smart Phones and Tablets.
- Wearables and Smartwatches.
- Smart TV and appliances.

Smart Cities

- Robotics and real time control.
- Predictive maintenance to collect and process sensor data on equipment health.

Healthcare

- Portable diagnostics equipment's
- Imaging Systems like CT and MRI use SoCs for advanced processing

Automotive

- Optimized Battery Management.
- Seamless Navigation Systems.
- Enable Safe And Intelligent Driving.

Energy And Utilities

- Smart Meters for efficient energy resource management
- Optimized solar and wind energy systems



Gaming & Entertainment

- Used in consoles for graphics and processing.
- VR/AR for immersive experiences.

Data Centers & Cloud Computing

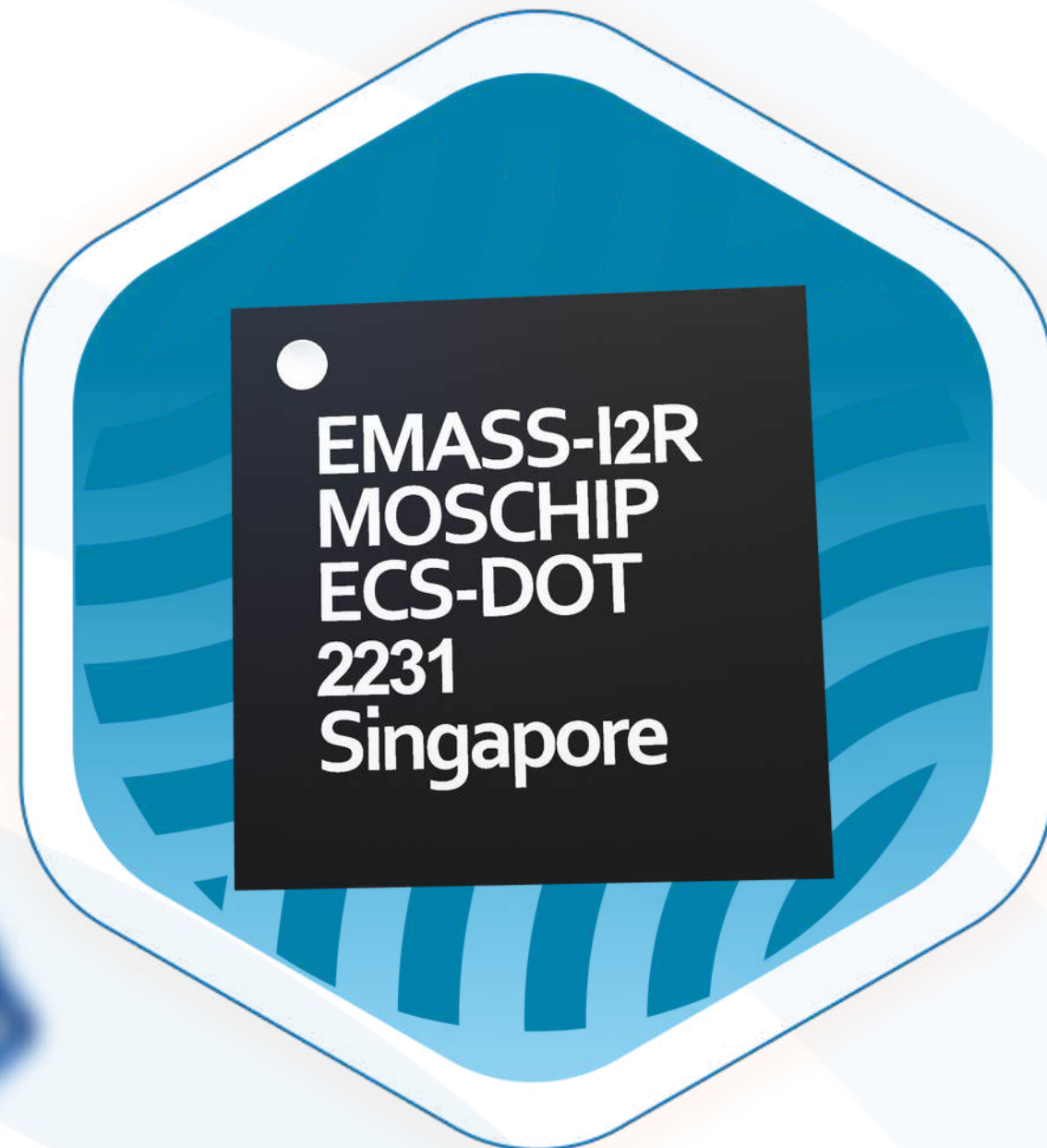
- Unprecedented growth in demand for cloud computing to support AI and ML usage

Telecommunications

- Networking communications such as Routers and Modems.
- Satellites for space communication.

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The EMASS Opportunity



1 An SoC With AI Capabilities

- **Problem** – Increasing demand for computational power that can handle AI workloads on the “edge”, faster data processing and analysis
- **Solution** – EMASS’s chip is capable of high AI workloads at its low power and form factor

2 Ultra Energy Efficient

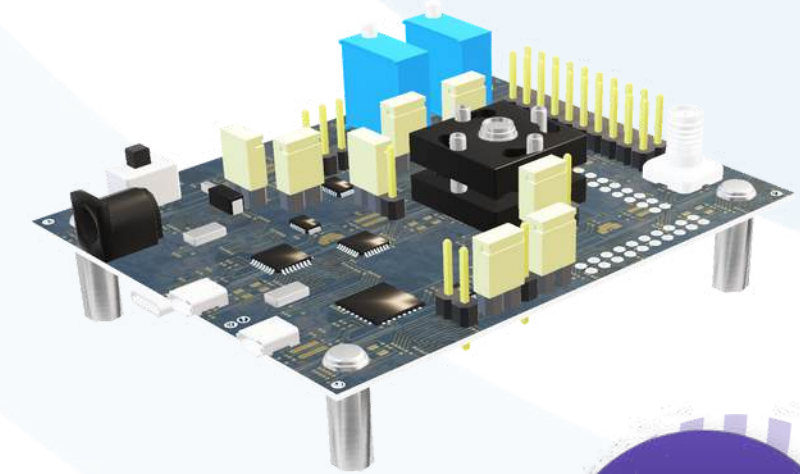
- **Problem** – Current Solutions struggle to run AI computations without high power consumption
- **Solution** – EMASS can run AI models efficiently allowing for a wide range of applications

3 High Levels Of Interoperability

- **Problem** – Integrating SoCs into edge devices can be complex
- **Solution** – EMASS’s RISC-V architecture is widely accepted with a strong community ensuring seamless integration, and future-proof solutions .

EMASS Superior Performance, Low Power, Small Form Factor

Leveraging The RISC-V Chip Architecture For Efficiency And Interoperability



Integrated
EMASS SoC with
AI & Accelerator
module

AI
Capacity

30 Giga-
Operations Per
second @ 50
MHz, 2mW

Up to 12
TOPs/Watt

Power
Efficiency

On-chip dense
memory

4 MBytes

Compressed AI
Model
< 2-bits

Hardware
support for
compressed AI
models

Physical size

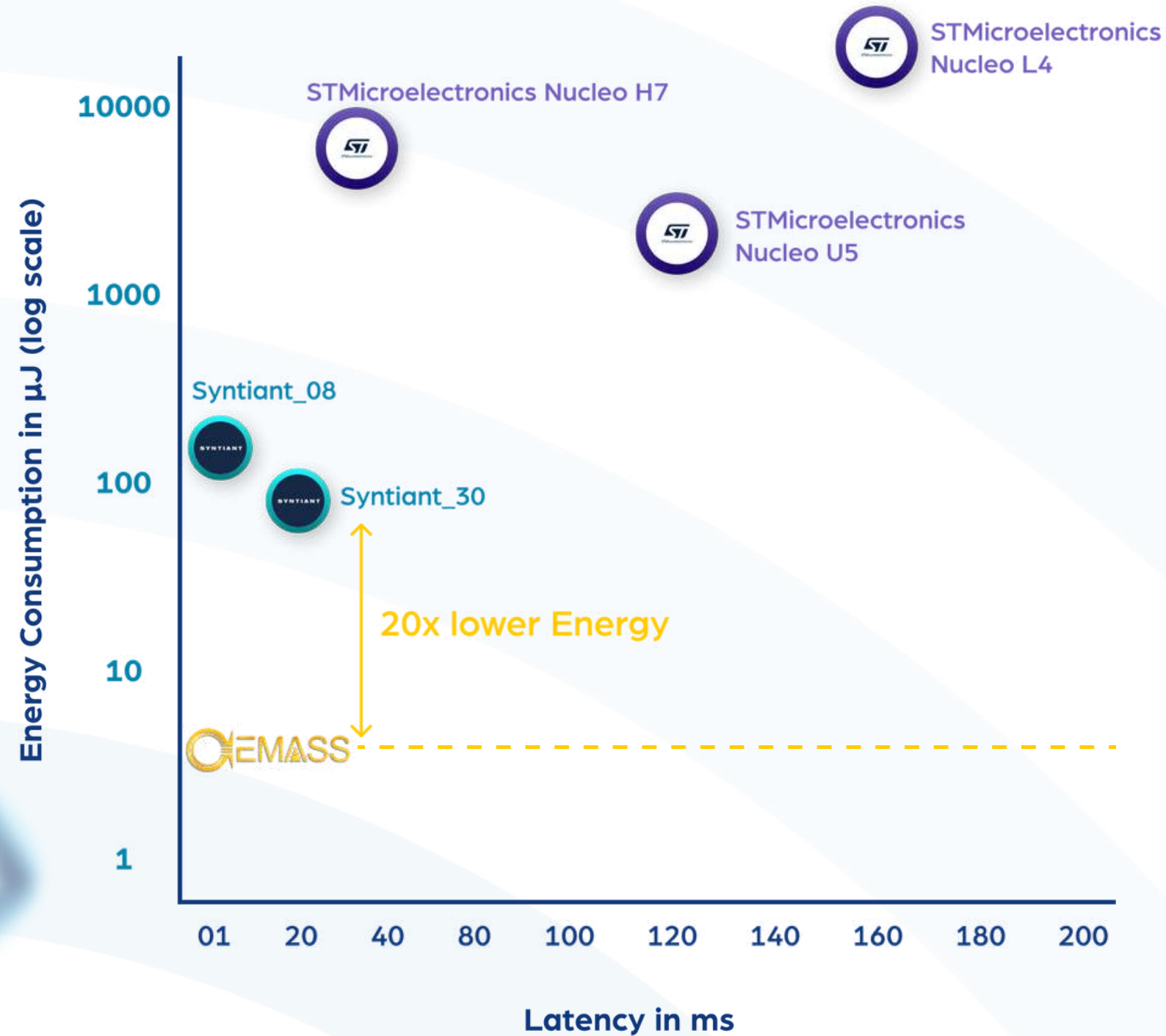
22nm
technology
with 7mm² die
area

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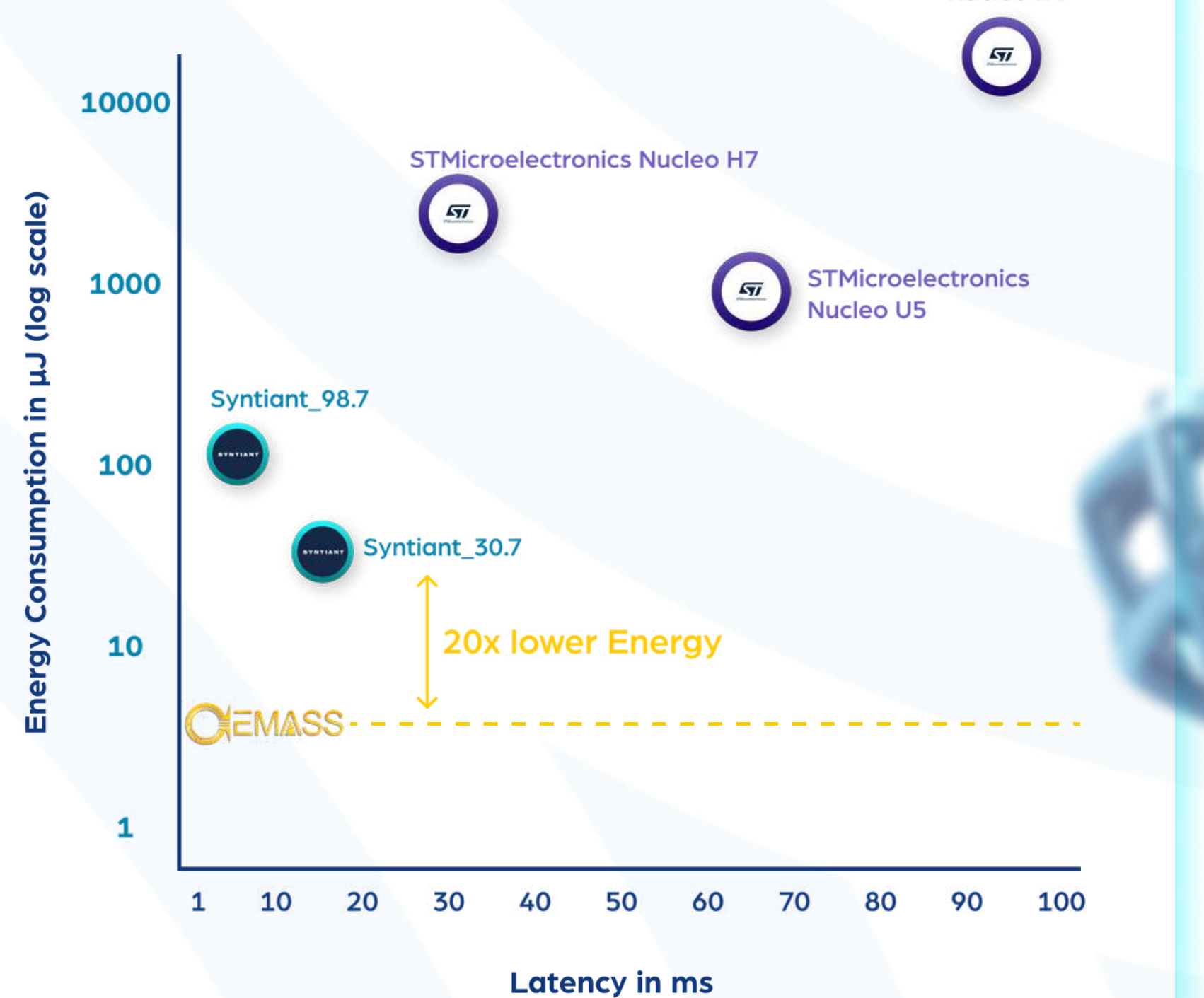
EMASS Exceptional AI Computation, 20X Lower Energy

EMASS's SOC has greater AI performance compared to today's leading chips

Image Classification



Visual Wake Words



EMASS Leads Industry Peers In AI Computation Tasks

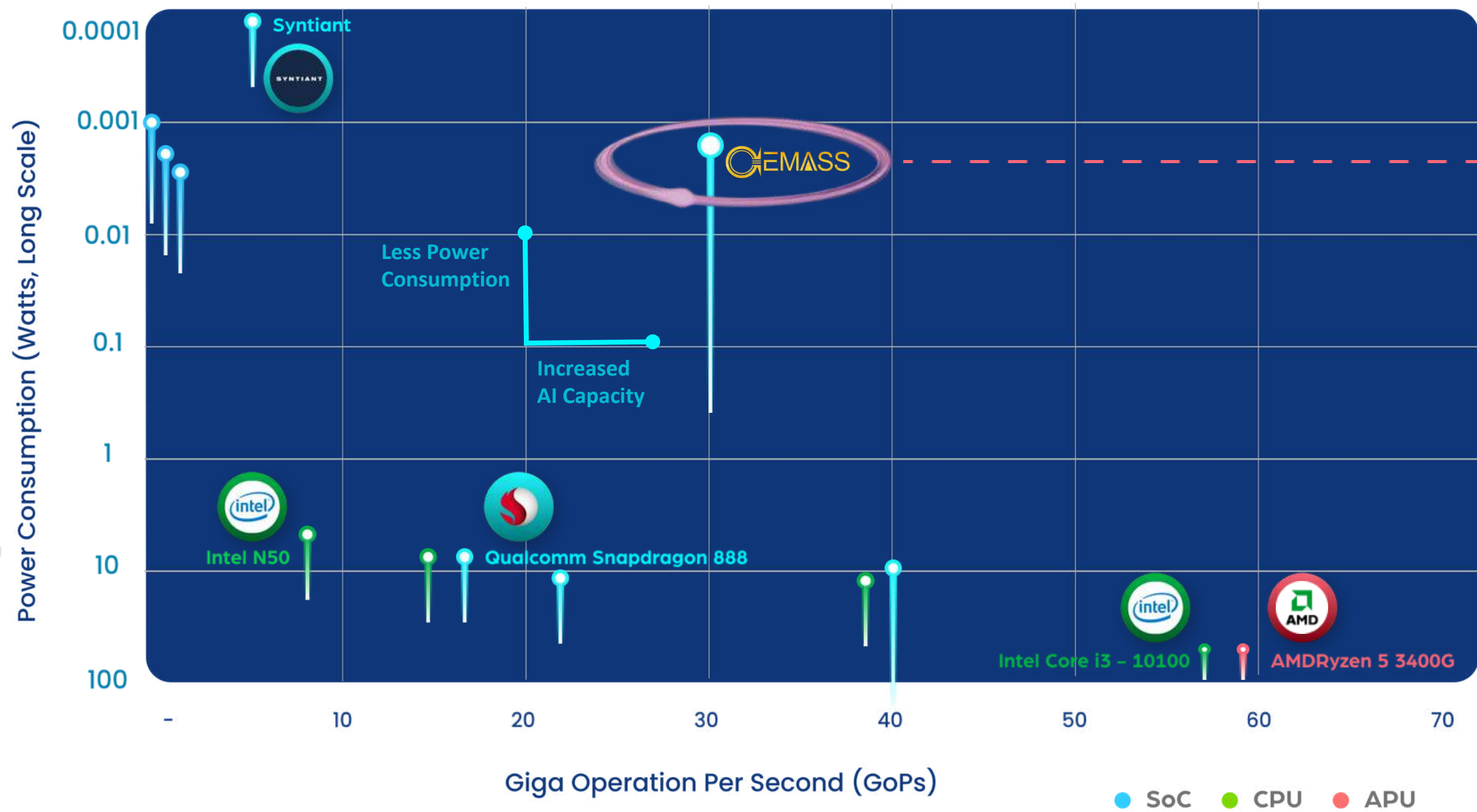
Company	Software Optimization	Target Application	AI Performance per Watt (Avg/Peak)	Power (Avg/Peak)	AI Performance	Max AI Parameters
 Nanoveu	YES	3D Vision, Health Monitoring, Wearable, Smart infrastructure	3/15 ToPs	0.1mW/10mW	30 GOPs	13 million
 Maxim Integrated	NO	Medical, Patches, Wearable	1.6/64 GoPs	50mW/2W	3.2 GOPs	3.5 million
 Himax	NO	Vision, Speech, Gesture, Agriculture, Retail	40/320 GoPs	2.5mW/20mW	0.8 GOPs	500 K
 Syntiant	NO	Vision, Smart home, Smartwatches	0.1/1 ToPs	7/30mW	6.4 GOPs	7 Million
 Ambiq	NO	Smart home, Smart watches, Fitness trackers, Animal tracker, Voice remote	240/133 GoPs	1mW/1.8mW	0.24 GOPs	1 Million
 Eta Compute	NO	Vision	200 GoPs	2mW	0.4 GOPs	256 K

*GoPs ≈ Clock Speed (GHz) × Instructions Per Cycle (IPC) × Number Of Cores

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EMASS Delivers Exceptional Energy Efficiency

EMASS's SOC has greater AI performance compared to today's leading chips



EMASS SoC: Power-Efficient AI For Next-Gen IoT

- Complete AI Capability – EMASS SoC delivers full AI operations with top power efficiency.
- Optimized for IoT – Ideal for battery-sensitive devices without performance loss or extra power drain.
- Seamless Integration – No hardware modifications required, enabling next-gen IoT development.

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EMASS Has Leading Energy Efficiency Compared To Peers

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Selected Chip Performances

Company	Chip	Chip Type	Target Industry	Max Performance per Watt	Power Consumption(TBP)	Max Performance
NANOVEU	EMASS	SOC	IoT, Wearables, Drones Artificial Intelligence	3-15 TOPS	0.1 – 10 MilliWatts	~30 GoPs
AMD	Ryzen 5 3400G	APU	Computing	~0.91 TOPS	65 Watts	~59 ToPs
INTEL	Processor N50	CPU	IoT, Chromebook	~0.53 TOPS	75 Watts	~40 ToPs
ARM	Cortex-A53	CPU	Smartphone, Tablets, Wearables, IoT	~0.0019 TOPS	7.5 Watts	~14 GoPs
QUALCOMM	Snapdragon 888	SOC	Artificial Intelligence, Wearables, Smartphone	~2.1 TOPS	8 Watts	~17 ToPs
BROADCOM	BCM2712	CPU	Robotics, industrial automation, edge computing	~3.2 TOPS	12 Watts	~38 ToPs
MEDIATECH	Helio P60	SOC	Artificial Intelligence Processing, Smartphones	~4 TOPS	10 Watts	~40 ToPs
MARVELL	Octeon TX2	SOC	5G Networks & Data Centres	~0.67 TOPS	30 Watts	~20 ToPs

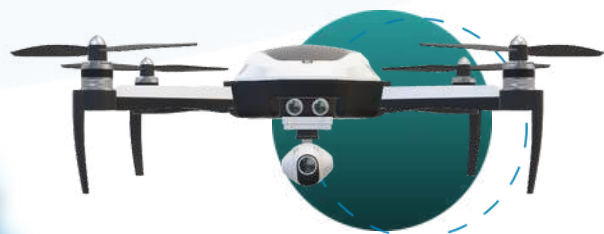
*GoPs ≈ Clock Speed (GHz) × Instructions Per Cycle (IPC) × Number Of Cores

EMASS Expands Market Opportunities for Nanoveu



Smartwatch

- Live Biometric Processing – Non-invasive oxygen, hydration, and blood glucose analysis.
- Predictive Diagnosis – Early disease detection.



Drones

- AI Self-Navigating Drones – For crop and livestock monitoring.
- Predictive Harvesting – Using multi-spectral and hyper-spectral data

A large circular graphic with a red-to-blue gradient border. Inside, a black square contains white text: 'EMASS-I2R', 'MOSCHIP', 'ECS-DOT', '2231', and 'Singapore'. Below the square, the text 'EMASS SoC Integration' is written in blue, followed by 'Embeds AI in devices with low power and no hardware upgrades.' in black.

EMASS-I2R
MOSCHIP
ECS-DOT
2231
Singapore

EMASS SoC Integration
Embeds AI in devices with low power and no hardware upgrades.



Medical Devices

- 2D to 3D Models – Instant scans and integrated medical imaging.
- Real-Time Diagnostics – For pacemakers and cochlear implants.



Glasses & Lens

- 2D to Augmented 3D – Virtual FaceTime and calls.
- Immersive AI Assistant – Enhanced experiences

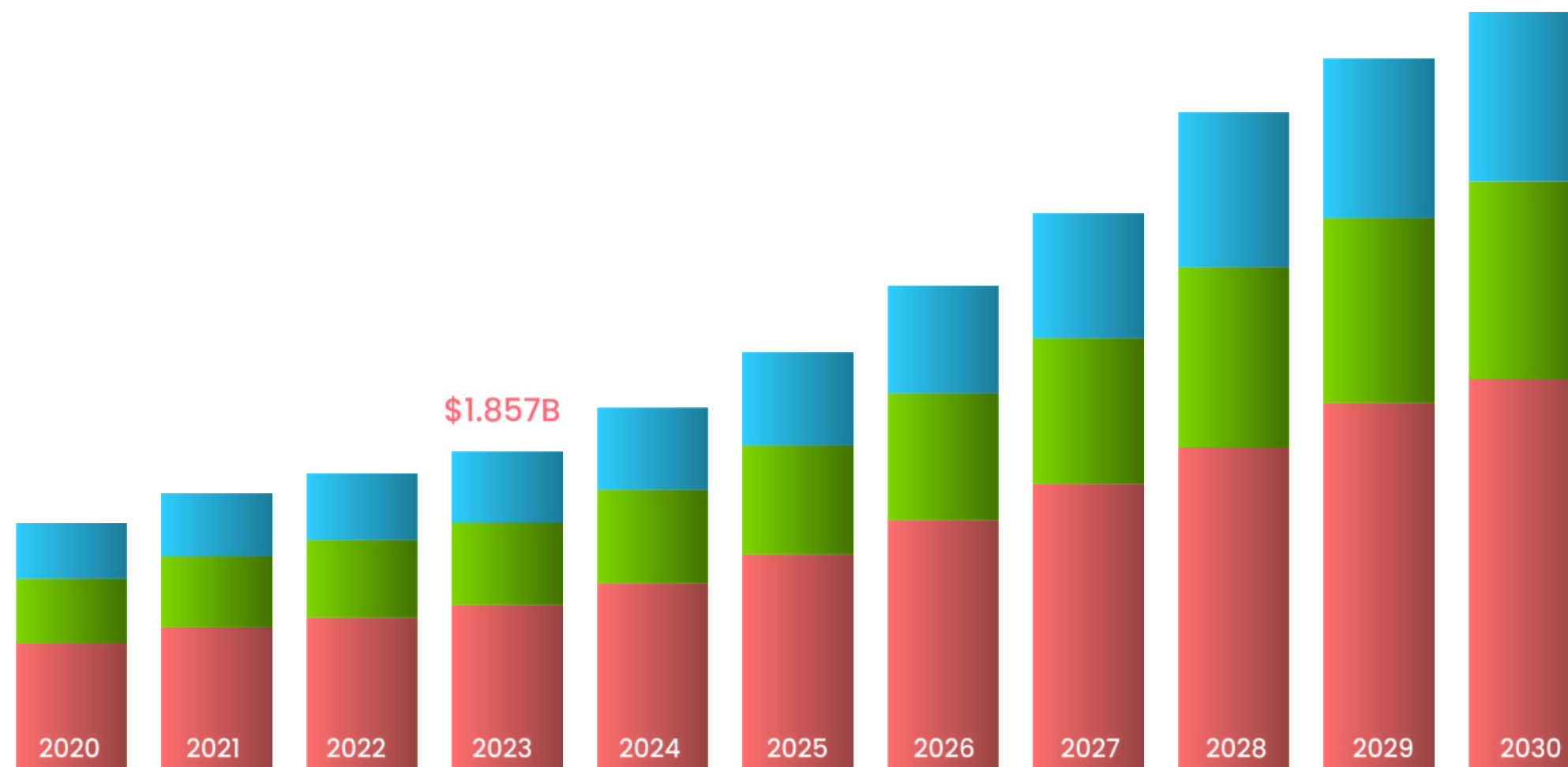
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Semiconductor & SoC Market Set For Rapid Growth

Powering The Future Of AI & Devices

System On Chip Market Size

By Type 2020-2030 (USD Billion)



Source: Grand View Research

● Digital ● Analog ● Mixed

SOC Powering The Future Of AI & Devices:

Essential for Next-Gen Tech – SoCs power AI, IoT, and autonomous systems with compact, high-performance computing.

Set to hit
\$325.7B
by 2030

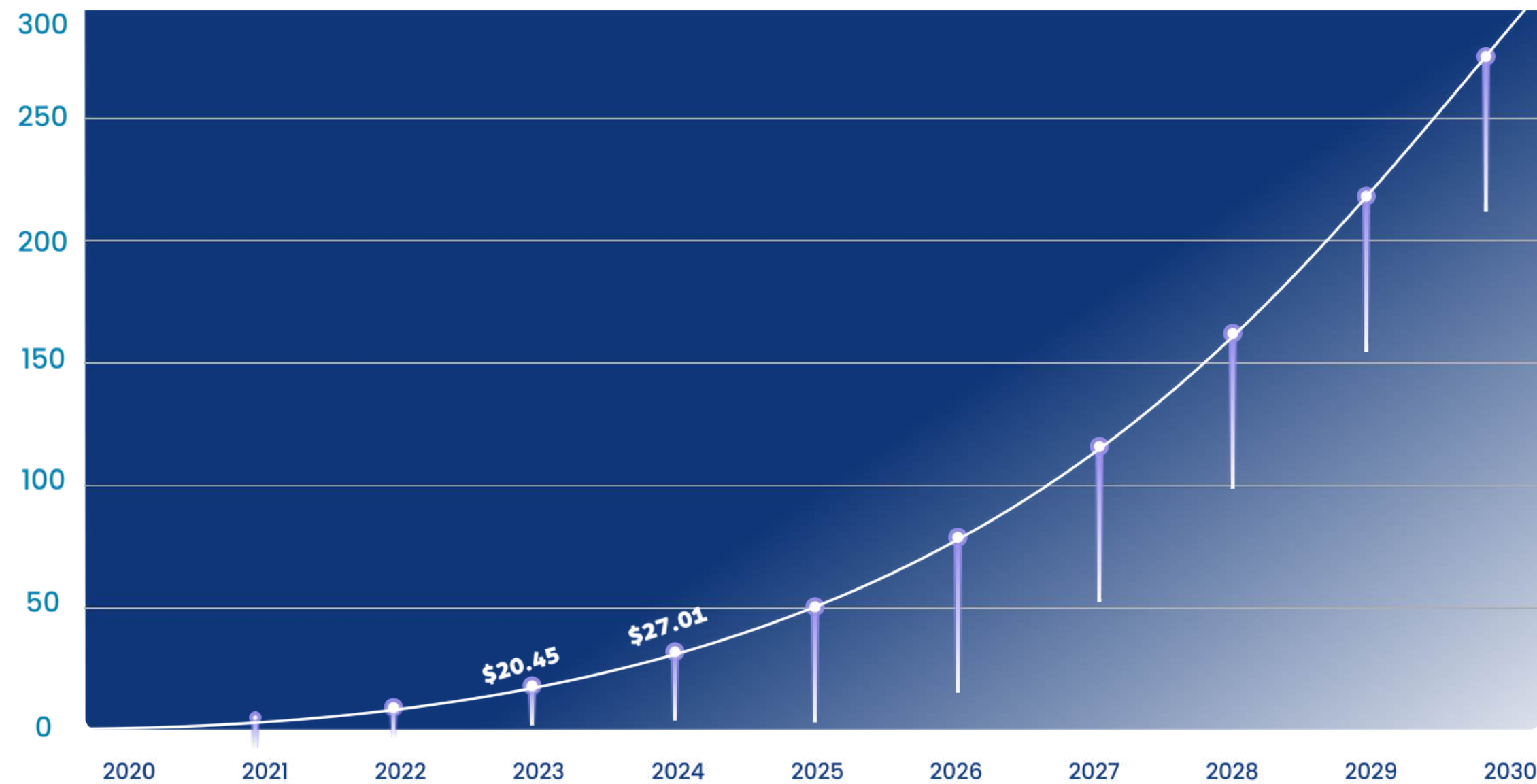
8.5% Global Market CAGR

Driven by AI, 5G, and smart devices.

Poised For Exponential Growth

Edge AI Smart And Efficient Computing For IOT

Edge AI Growth Rate



Source: Fortune Business Insights

Edge AI: Smart & Efficient Computing For IoT

Faster, Smarter AI – Powers real-time decisions for IoT, autonomous vehicles, and next-gen tech.

Expected To Reach

\$269.82B
by **2030**

33.3% CAGR

As AI moves to on-device processing.

EMASS Global Development and Collaboration Partners

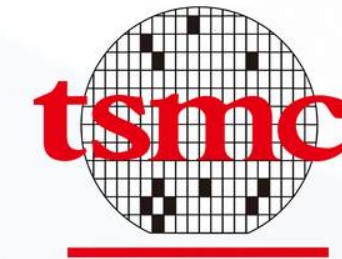
EMASS has been developed with the world's leading Chip manufacturers and partners



Early Backers, IP & Development



ReRAM Collaboration Partner



Taiwan Semiconductor Manufacturing Company
Market Cap: \$127



IC Fabrication, PCB Fabrication, Packaging

Fully Integrated Glasses Free 3D Experiences On Your Mobile Phone

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EyeFly3D App And AI Algorithm (Software)



EyeFly3D Screen Cover (Hardware)

EyeFly^{3D} Delivers Remarkable Glasses-free 3D To Smart Phones and Digital Displays

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Opportunity:

EyeFly 3D dramatically improves the engaging qualities of mobile content. It brings visual content to life allowing users to experience more immersive videos and pictures.



Key Problem:

There is an increasing opportunity to create more immersive content consumption in a sleek and easy-to-use form factor exemplified by the difficulty in traction within the VR space



Instant 3D Without Glasses

Converts standard 2D content into stunning 3D, no eyewear required.



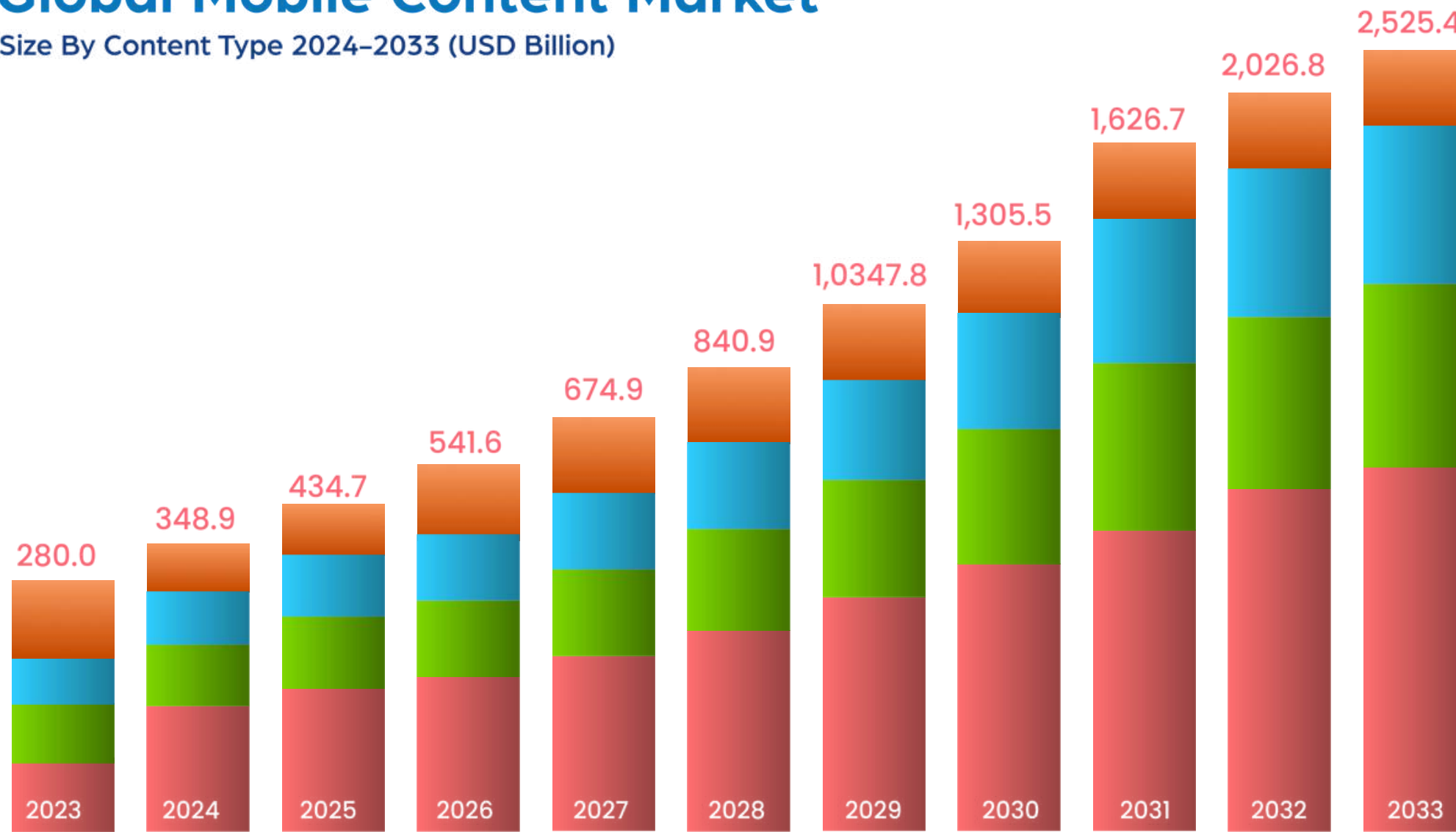
Communication

EyeFly 3D paving the way for 3D video calls, revolutionizing communication.

EyeFly 3D Can Impact Some Of The Fastest Growing Segments In Mobile

Global Mobile Content Market

Size By Content Type 2024-2033 (USD Billion)



Source: Market US

● Apps ● Games ● Music ● Others

EyeFly 3D Engagement

Enhances mobile experiences with glasses-free 3D content for richer interactions.

Set to hit

\$2.52T

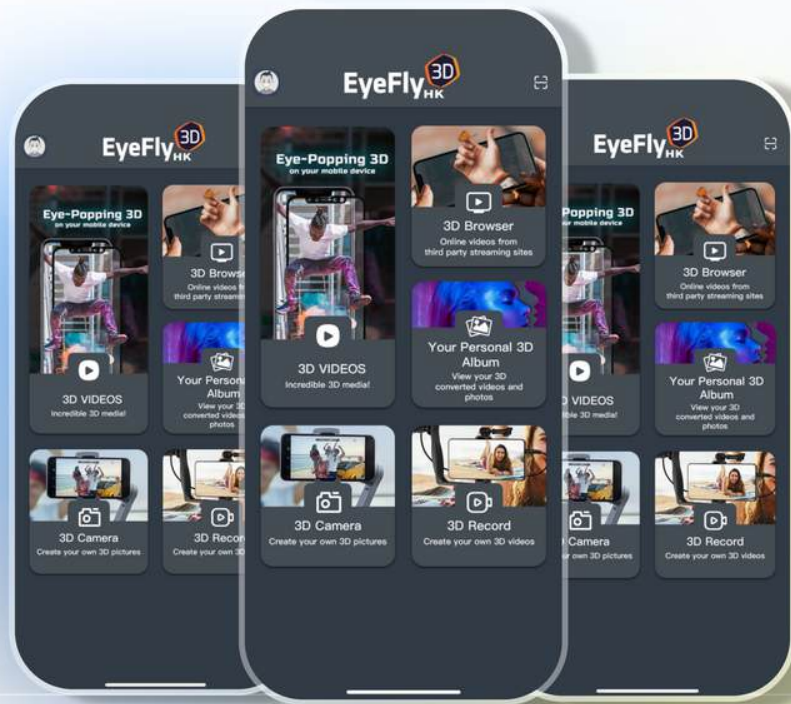
by 2033

24.6% CAGR

Driven by Mobile Apps and Digital Content

EyeFly^{3D} How Does It Work?

EyeFly^{3D} Is An Invisible Screen That Brings Your Content To Life



EyeFly3D App & AI Algorithm (Software)

- Proprietary Software – Converts Images And Videos From 2D To 3D
- Dynamic 3D Mapping – Adjusts Content Based On Screen Distance
- Social App – View And Share 3D Content



EyeFly3D Screen Cover (Hardware)

- Patented Nanotechnology – Superior 3D Experience
- Easy Apply Kit – Simple And Hassle-Free
- Brighter & Sharper – Outperforms Competitors

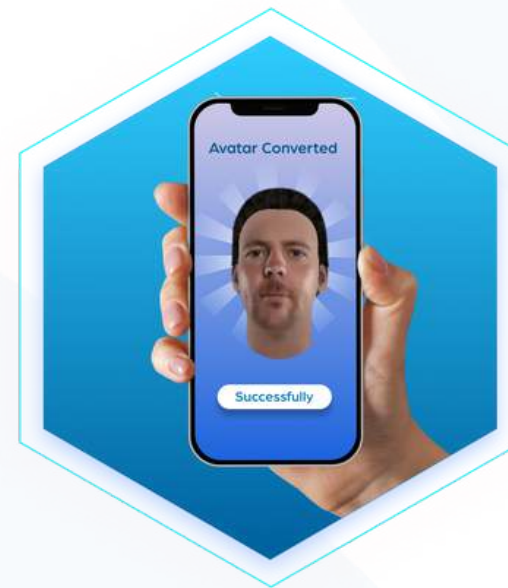
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Launching Soon EyeFly^{3D} App: Allowing users to Create and Share Engaging Glasses-Free 3D Content



Capture with Ease

Record 3D videos and photos using your phone or the EyeFly3D app.



Instant 3D Conversion

AI-powered 2D to 3D transformation in seconds.



Seamless Sharing

Share 3D videos and photos effortlessly.

Upcoming Features



Advertising



Streaming & Content



Video calling



Gaming



3D communities

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International Distribution & Expansion Underway

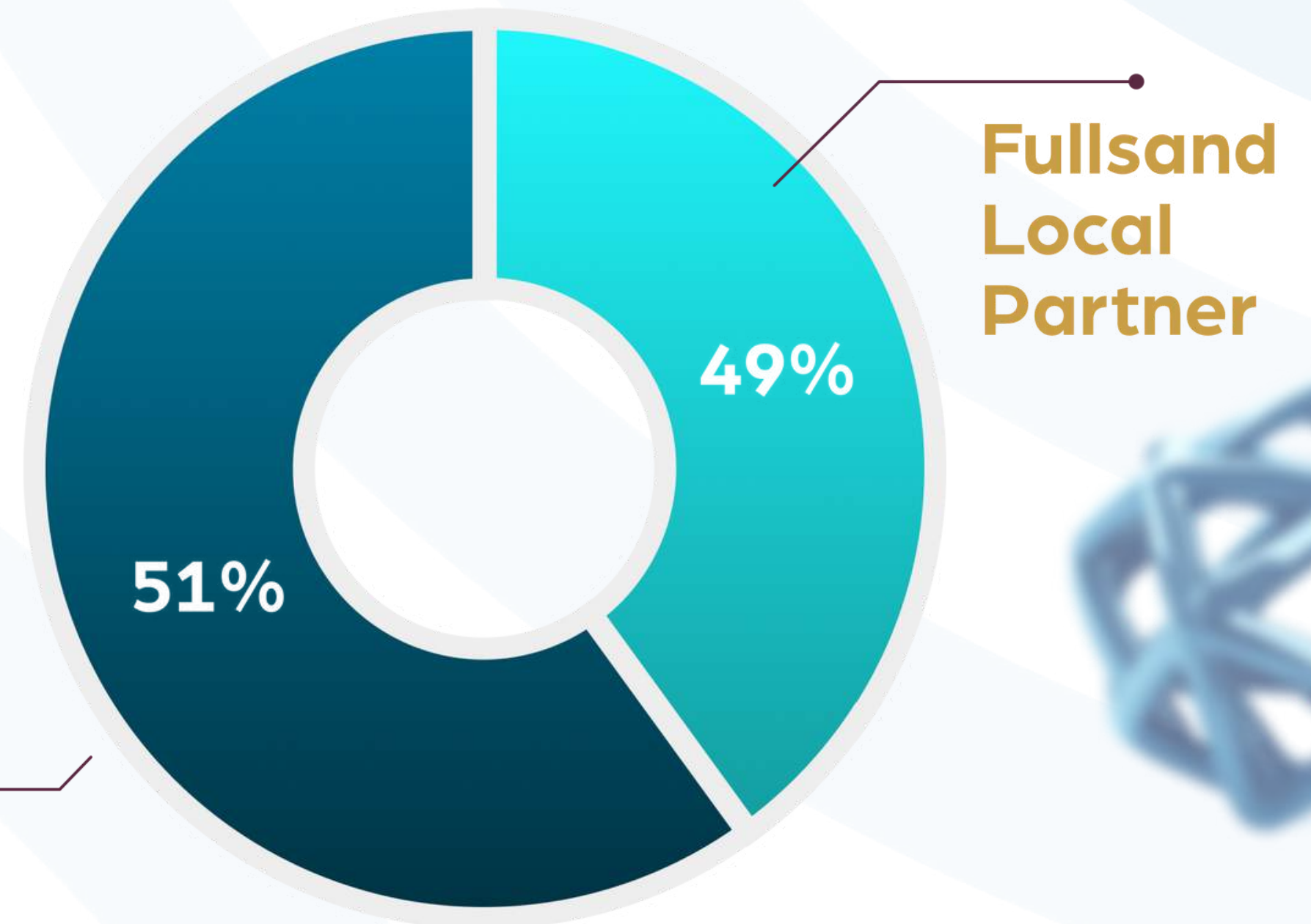
Key JV Terms:

- Global rights to technology development and distribution (except China).
- Nanoveu gains control over manufacturing, ensuring security and scalability.
- The JV speeds up the development and launch of new technologies worldwide.

Korean Partners: Rahum Nano Tech, Inc.

- Exclusive distributor of EyeFly3D in Korea. [1]
- Key focus on iPhone 16 Series and the latest Samsung Galaxy S Series.
- Seeking to expand markets for tablets and large format displays.

[1] <https://wcsecure.weblink.com.au/pdf/NVU/02812220.pdf>



nanoveu

FullVeU

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Nanoveu's planned integration of: **EMASS** x **EyeFly^{3D}** **To bring glasses-free 3D to more devices**

Identification of Target Devices:

01

EMASS's energy-efficient SoCs power EyeFly3D for smooth, high-quality 3D on portable devices without draining battery.

EMASS-I2R
 MOSCHIP
 ECS-DOT
 2231
 Singapore

Integration of Chip

02

EMASS will develop the chip for the target smart device enabling more engaging content on tablets, TVs etc.



Enhanced 3D Experiences

03

EMASS SoCs speed up 2D to 3D conversion, allowing EyeFly3D to render content instantly on any screen without cloud delays.



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Thank You

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Singapore Office

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